

SN74LVTH32373-EP

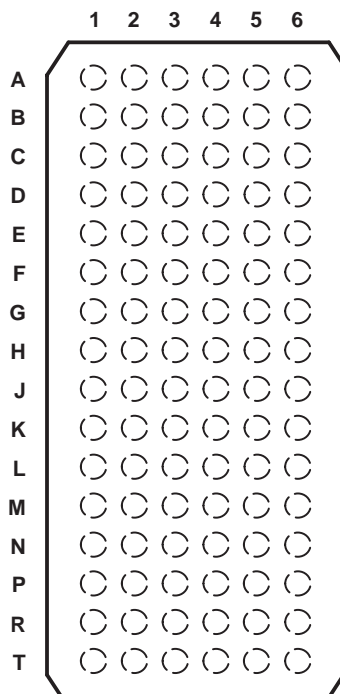
3.3-V ABT 32-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Member of the Texas Instruments Widebus+™ Family**
- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation**
- **Typical V_{OLP} (Output Ground Bounce)**
 $<0.8\text{ V}$ at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Supports Mixed-Mode Signal Operation**
 (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Supports Unregulated Battery Operation Down To 2.7 V**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

**GKE PACKAGE
(TOP VIEW)**



terminal assignments

| | 1 | 2 | 3 | 4 | 5 | 6 |
|---|-----|-----|-------------------|------------|-----|-----|
| A | 1Q2 | 1Q1 | 1 \overline{OE} | 1LE | 1D1 | 1D2 |
| B | 1Q4 | 1Q3 | GND | GND | 1D3 | 1D4 |
| C | 1Q6 | 1Q5 | 1 V_{CC} | 1 V_{CC} | 1D5 | 1D6 |
| D | 1Q8 | 1Q7 | GND | GND | 1D7 | 1D8 |
| E | 2Q2 | 2Q1 | GND | GND | 2D1 | 2D2 |
| F | 2Q4 | 2Q3 | 1 V_{CC} | 1 V_{CC} | 2D3 | 2D4 |
| G | 2Q6 | 2Q5 | GND | GND | 2D5 | 2D6 |
| H | 2Q7 | 2Q8 | 2 \overline{OE} | 2LE | 2D8 | 2D7 |
| J | 3Q2 | 3Q1 | 3 \overline{OE} | 3LE | 3D1 | 3D2 |
| K | 3Q4 | 3Q3 | GND | GND | 3D3 | 3D4 |
| L | 3Q6 | 3Q5 | 2 V_{CC} | 2 V_{CC} | 3D5 | 3D6 |
| M | 3Q8 | 3Q7 | GND | GND | 3D7 | 3D8 |
| N | 4Q2 | 4Q1 | GND | GND | 4D1 | 4D2 |
| P | 4Q4 | 4Q3 | 2 V_{CC} | 2 V_{CC} | 4D3 | 4D4 |
| R | 4Q6 | 4Q5 | GND | GND | 4D5 | 4D6 |
| T | 4Q7 | 4Q8 | 4 \overline{OE} | 4LE | 4D8 | 4D7 |



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description/ordering information

The SN74LVTH32373 is a 32-bit transparent D-type latch designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. This device is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

This device can be used as four 8-bit latches, two 16-bit latches, or one 32-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

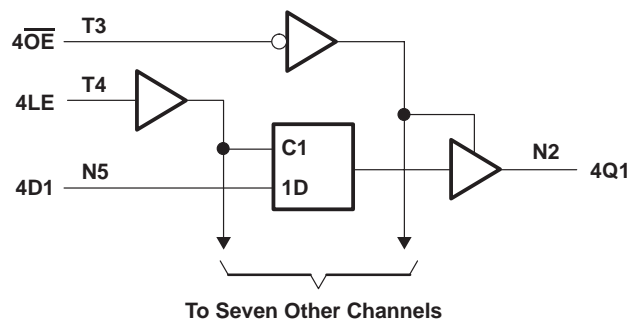
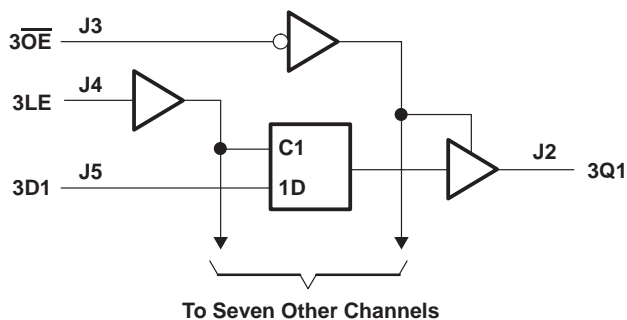
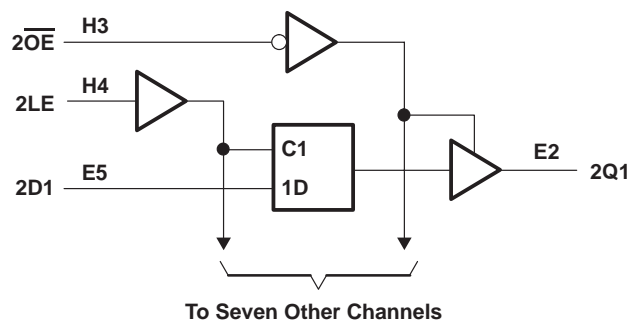
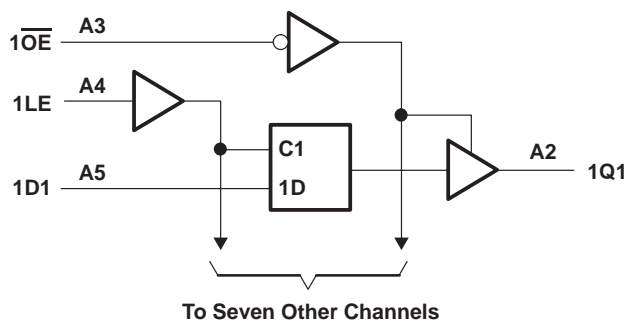
| TA | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|-------------|---------------|-----------------------|------------------|
| –40°C to 85°C | LFBGA – GKE | Tape and reel | CLVTH32373IGKERE | L373EP |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each 8-bit latch)

| INPUTS | | | OUTPUT Q |
|-----------------|----|---|-------------|
| \overline{OE} | LE | D | |
| L | H | H | H |
| L | H | L | L |
| L | L | X | Q_0 |
| H | X | X | Z |

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | –0.5 V to 4.6 V |
| Input voltage range, V_I (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high state, V_O (see Note 1) | –0.5 V to $V_{CC} + 0.5$ V |
| Current into any output in the low state, I_O | 128 mA |
| Current into any output in the high state, I_O (see Note 2) | 64 mA |
| Input clamp current, I_{IK} ($V_I < 0$) | –50 mA |
| Output clamp current, I_{OK} ($V_O < 0$) | –50 mA |
| Package thermal impedance, θ_{JA} (see Note 3) | 40°C/W |
| Storage temperature range, T_{stg} (see Note 4) | –65°C to 150°C |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See Figure 1 for additional information on thermal derating.

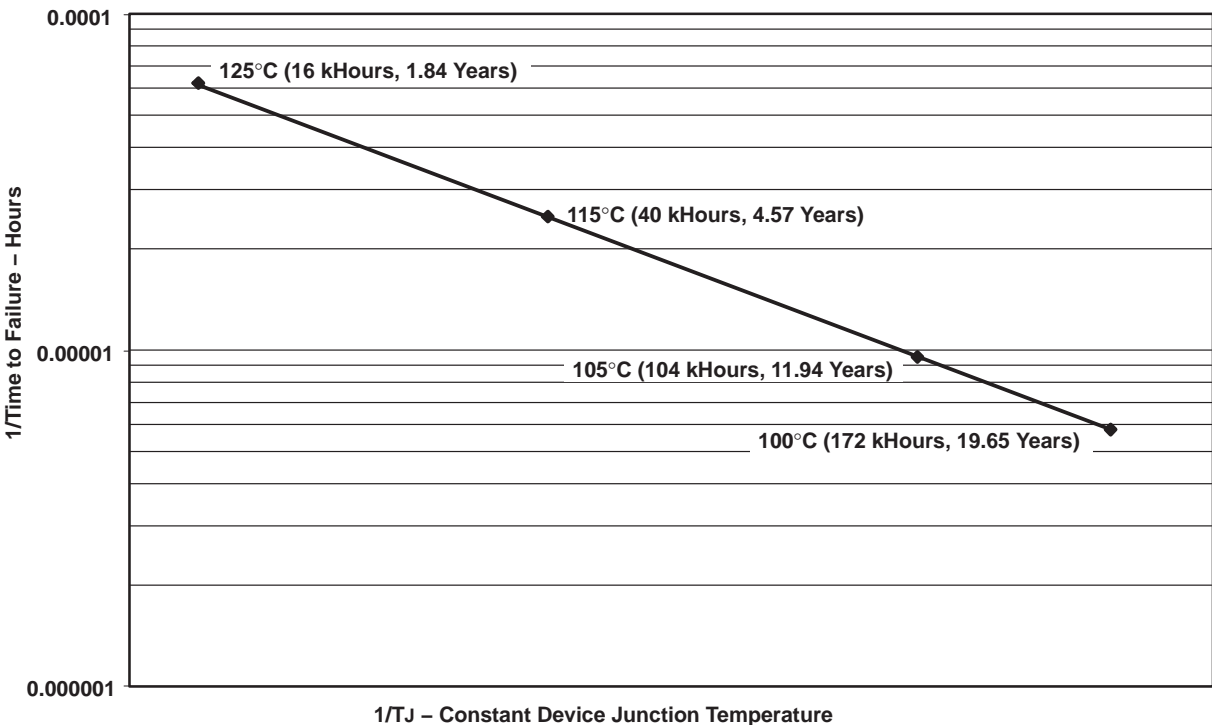


Figure 1. Estimated Wirebond Life
Based on Elevated-Temperature Kirkendall-Voiding Failure Mode

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recommended operating conditions (see Note 5)

| | | | MIN | MAX | UNIT |
|---------------------|------------------------------------|-----------------|-----|-----|------|
| V _{CC} | Supply voltage | | 2.7 | 3.6 | V |
| V _{IH} | High-level input voltage | | 2 | | V |
| V _{IL} | Low-level input voltage | | | 0.8 | V |
| V _I | Input voltage | | | 5.5 | V |
| I _{OH} | High-level output current | | | −32 | mA |
| I _{OL} | Low-level output current | | | 64 | mA |
| Δt/Δv | Input transition rise or fall rate | Outputs enabled | | 10 | ns/V |
| Δt/ΔV _{CC} | Power-up ramp rate | | 200 | | μs/V |
| T _A | Operating free-air temperature | | −40 | 85 | °C |

NOTE 5: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP† | MAX | UNIT |
|----------------------|-------------------------|---|------------------|--------------|------|-----------|---------------|
| V_{IK} | | $V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$ | | | | -1.2 | V |
| V_{OH} | | $V_{CC} = 2.7\text{ V to } 3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$ | | $V_{CC}-0.2$ | | | V |
| | | $V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$ | | 2.4 | | | |
| | | $V_{CC} = 3\text{ V}$, $I_{OH} = -32\text{ mA}$ | | 2 | | | |
| V_{OL} | $V_{CC} = 2.7\text{ V}$ | $I_{OL} = 100\text{ }\mu\text{A}$ | | | | 0.2 | V |
| | | $I_{OL} = 24\text{ mA}$ | | | | 0.5 | |
| | $V_{CC} = 3\text{ V}$ | $I_{OL} = 16\text{ mA}$ | | | | 0.4 | |
| | | $I_{OL} = 32\text{ mA}$ | | | | 0.5 | |
| | | $I_{OL} = 64\text{ mA}$ | | | | 0.55 | |
| I_I | | $V_{CC} = 0\text{ or } 3.6\text{ V}$, $V_I = 5.5\text{ V}$ | | | | 10 | μA |
| | Control inputs | $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}\text{ or GND}$ | | | | ± 1 | |
| | Data inputs | $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ | | | | 1 | |
| | | $V_I = 0$ | | | | -5 | |
| I_{off} | | $V_{CC} = 0$, $V_I\text{ or } V_O = 0\text{ to } 4.5\text{ V}$ | | | | ± 100 | μA |
| $I_{I(hold)}$ | Data inputs | $V_{CC} = 3\text{ V}$, $V_I = 0.8\text{ V}$ | | 75 | | | μA |
| | | $V_I = 2\text{ V}$ | | -75 | | | |
| | | $V_{CC} = 3.6\text{ V}^{\ddagger}$, $V_I = 0\text{ to } 3.6\text{ V}$ | | | | ± 500 | |
| I_{OZH} | | $V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$ | | | | 5 | μA |
| I_{OZL} | | $V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$ | | | | -5 | μA |
| I_{OZPU} | | $V_{CC} = 0\text{ to } 1.5\text{ V}$, $V_O = 0.5\text{ V to } 3\text{ V}$, $\overline{OE} = \text{don't care}$ | | | | ± 100 | μA |
| I_{OZPD} | | $V_{CC} = 1.5\text{ V to } 0$, $V_O = 0.5\text{ V to } 3\text{ V}$, $\overline{OE} = \text{don't care}$ | | | | ± 100 | μA |
| I_{CC} | | $V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$ | Outputs high | | | 0.38 | mA |
| | | | Outputs low | | | 10 | |
| | | | Outputs disabled | | | 0.38 | |
| ΔI_{CC}^{\S} | | $V_{CC} = 3\text{ V to } 3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$ | | | | 0.2 | mA |
| C_i | | $V_I = 3\text{ V or } 0$ | | | | 3 | pF |
| C_o | | $V_O = 3\text{ V or } 0$ | | | | 9 | pF |

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than $V_{CC}\text{ or GND}$.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

| | | $V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$ | | $V_{CC} = 2.7\text{ V}$ | | UNIT |
|----------|---|---|-----|-------------------------|-----|------|
| | | MIN | MAX | MIN | MAX | |
| t_w | Pulse duration, LE high | 3 | | 3 | | ns |
| t_{su} | Setup time, data before LE \downarrow | 1 | | 0.6 | | ns |
| t_h | Hold time, data after LE \downarrow | 1 | | 1.1 | | ns |



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$ | | | $V_{CC} = 2.7\text{ V}$ | | UNIT |
|-------------|-----------------|----------------|---|------|-----|-------------------------|-----|------|
| | | | MIN | TYP† | MAX | MIN | MAX | |
| t_{PLH} | D | Q | 1.5 | 2.7 | 3.8 | 4.2 | | ns |
| t_{PHL} | | | 1.5 | 2.5 | 3.6 | 4 | | |
| t_{PLH} | LE | Q | 2.1 | 3 | 4.3 | 4.8 | | ns |
| t_{PHL} | | | 2.1 | 2.9 | 4 | 4 | | |
| t_{PZH} | \overline{OE} | Q | 1.5 | 2.8 | 4.3 | 5.1 | | ns |
| t_{PZL} | | | 1.5 | 2.8 | 4.3 | 4.7 | | |
| t_{PHZ} | \overline{OE} | Q | 2.4 | 3.5 | 5 | 5.4 | | ns |
| t_{PLZ} | | | 2 | 3.2 | 4.7 | 4.8 | | |
| $t_{sk(o)}$ | | | | | 0.5 | | | ns |

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

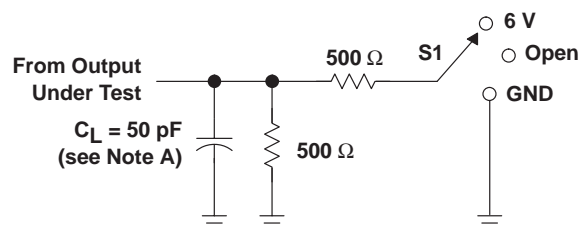
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WITH 3-STATE OUTPUTS

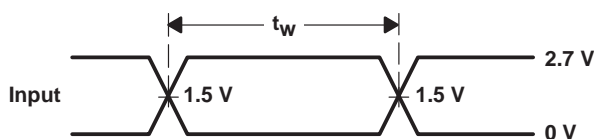
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PARAMETER MEASUREMENT INFORMATION

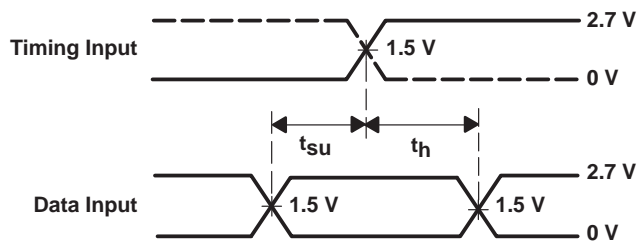


LOAD CIRCUIT

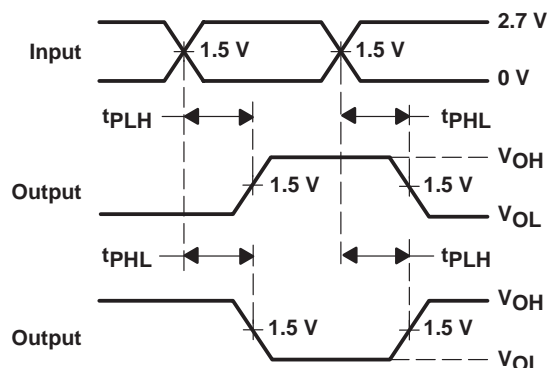
| TEST | S1 |
|-------------------|------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | 6 V |
| t_{PHZ}/t_{PZH} | GND |



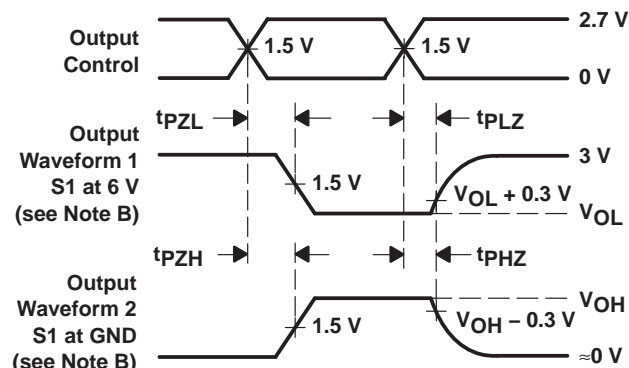
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|-------------------|---------------|--------------|--------------------|------|----------------|-----------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| CLVTH32373IGKEREP | ACTIVE | LFBGA | GKE | 96 | 1000 | TBD | SNPB | Level-3-220C-168 HR | -40 to 85 | L373EP | Samples |
| V62/04721-01XA | ACTIVE | LFBGA | GKE | 96 | 1000 | TBD | SNPB | Level-3-220C-168 HR | -40 to 85 | L373EP | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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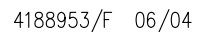
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OTHER QUALIFIED VERSIONS OF SN74LVTH32373-EP :

- Catalog: [SN74LVTH32373](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO-205 variation CC.
D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

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Products

| | |
|------------------------------|--|
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